PCN Number:	20160408001	**PCN Date:**	4/12/2016
Title:	Qualification of Additional Fab (RFAB) and Additional Assembly/Test (TI Clark) sites for Select Devices		
Customer Contact:	PCN Manager	**Dept:**	Quality Services
Proposed 1st Ship Date:	7/12/2016	**Estimated Sample Availability:**	Provided upon Request

Change Type:

☒	Assembly Site	☐	Assembly Process	☒	Assembly Materials
☐	Design	☐	Electrical Specification	☐	Mechanical Specification
☒	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☒	Wafer Fab Site	☐	Wafer Fab Materials	☐	Wafer Fab Process
		☐	Part number change		

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of RFAB as an additional fab site and TI Clark as an additional assembly/test site for the devices listed below. Device construction differences between the various sites are as follows:

What (Package Designator)	MLA	CRS	TI Clark
Mount Compound (RHB)	4205846	SID#435143	**4207768**
Mount Compound (RGZ)	n/a	SID#435143	**4207123**

Fab Details					
Current Fab Site	**Process**	**Wafer Diameter**	**Additional Fab Site**	**Process**	**Wafer Diameter**
DP1DM5	C05	200 mm	RFAB	C05	300 mm

Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.

Reason for Change:

Continuity of Supply

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None

Anticipated impact on Material Declaration

☐	No Impact to the Material Declaration	☒	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI ECO website.

Changes to product identification resulting from this PCN:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (21L)	Assembly City
TI Malaysia	MLA	MYS	Kuala Lumpur
Carsem	CRS	MYS	Jelapang
TI Clark	**QAB**	**PHL**	**Angeles City**

Fab Sites

Chip Sites	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
DP1DM5	DM5	USA	Dallas

New

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
RFAB	**RFB**	**USA**	**Richardson**

Sample product shipping label (not actual product label)

Topside Device marking:
Assembly site code for MLA= K
Assembly site code for CRS = W
Assembly site code for QAB = I

Product Affected

TLV320AIC3004IRHBR	TLV320AIC3105IRHBR	TLV320AIC3106IRGZR	TLVAIC3105IRHBRG4
TLV320AIC3004IRHBT	TLV320AIC3105IRHBT	TLV320AIC3106IRGZT	

TEXAS INSTRUMENTS

TI Information
Selective Disclosure

Qualification Report

TLV320AIC3106/5/6RGZ in RFAB and Clark (release the G2TIAIC39A die in Clark)

Approve Date 05-Apr-2016

Product Attributes

Attributes	Qual Device: TLV320AIC3106IRGZR	QBS Process Reference: VSP6825BZRC	QBS Package Reference: SN65LVCP40RGZ	QBS Package Reference: TPS62402DRCR _CU_WIRE
Assembly Site	CLARK-AT	PHI	CLARK-AT	CLARK-AT
Package Family	QFN	JRBGA	QFN	SON
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0
Wafer Fab Supplier	RFAB	HIJI, RFAB	FFAB	FFAB
Wafer Process	1118C05	1833C05, LBC4	BICOM3	3370A12

- QBS: Qual By Similarity
- Qual Device TLV320AIC3106IRGZR is qualified at LEVEL2-260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TLV320AIC3106IRGZR	QBS Process Reference: VSP6825BZRC	QBS Package Reference: SN65LVCP40RGZ	QBS Package Reference: TPS62402DRCR _CU_WIRE
AC	Autoclave 121C	96 Hours	-	-	1/77/0	1/77/0
ED	Electrical Characterization	Per Datasheet Parameters	Pass	-	-	-
HAST	Biased HAST,130C/85%RH	96 Hours	-	3/230/0	1/77/0	-
HTOL	Life Test, 140C	480 Hours	-	3/231/0	-	-
HTOL	Life Test, 155C	240 Hours	-	-	1/77/0	-
HTSL	High Temp. Storage Bake, 170C	420 Hours	-	3/231/0	1/77/0	1/77/0
PD	Physical Dimensions	--	-	-	1/5/0	1/5/0
TC	Temperature Cycle, -65/150C	500 Cycles	-	3/231/0	1/77/0	1/77/0
TS	Thermal Shock, -65/150C	500 Cycles	-	-	-	1/77/0
WBP	Bond Pull	Wires	1/76/0	-	1/76/0	1/76/0
WBS	Wire Bond Shear	Wires	1/76/0	-	1/76/0	1/76/0

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
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